BigTwin SuperServer SYS-222BT-HNC8R

2U 4-Node BigTwin with 6 hot-swap 2.5" NVMe/SAS/SATA drives per node

More details here

Key Applications

Container-as-a-Service; Application Accelerator, Diskless HPC Clusters, All-Flash Hyperconverged Infrastructure,



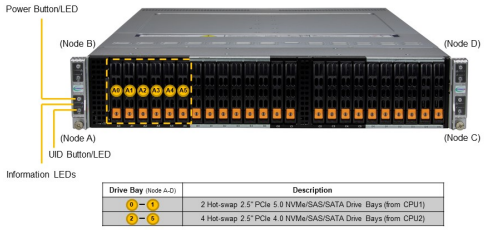
Key Features

- Dual Socket E2 Intel® Xeon® 6 6700 series processors with E-cores up to 205W with air cooling or 330W with liquid cooling
  Single CPU configurations supported while maintaining all expansion slot functionality;
- Up to 16 DIMMs supporting up to 4TB DDR5-6400 in 1DPC;
- Flexible networking with OCP 3.0 AIOM slot;
- Up to 2 PCIe 5.0 x16 LP slots
  Internal PCIe 5.0 for 2x NVMe M.2 support onboard
  Optional 4x NVMe M.2 support onboard with built-in HW RAID1 feature via SCC-A2NM2241GH-B1;
- Up to 6 front hot-swap 2.5" NVMe/SAS drive bays
  Built-in SAS3 Support via Broadcom 3808; IT Mode;
- Four hot-pluggable systems (nodes) in a 2U form factor. Each node supports the following:;

Form Factor	2U Rackmount Enclosure: 449 x 88 x 730mm (17.68" x 3.47" x 28.75") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	Dual Socket E2 (LGA-4710) Intel® Xeon® 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache per CPU
System Memory	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 2TB 6400MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 6 bays • 2 front hot-swap 2.5" PCIe 5.0 NVMe/SAS drive bays • 4 front hot-swap 2.5" PCIe 4.0 NVMe/SAS drive bays M.2: 2 M.2 PCIe 5.0 x4 NVMe slots (M-key 22110(default); VROC required for RAID)
Expansion Slots	Default • 2 PCIe 5.0 x16 LP slots • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)
On-Board Devices	SAS: SAS (12Gbps) via Broadcom® 3808; (IT mode) Chipset: System on Chip Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port USB: 2 USB 3.0 Gen2 Type-A ports(Rear) Video: 1 VGA port

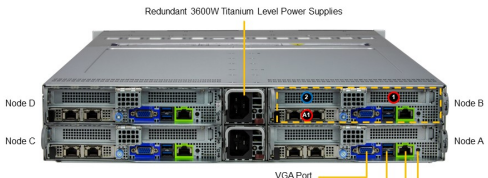
©2024 Copyright Super Micro Computer, Inc. All rights reserved. *Product specifications may change without notice

(Front View – System)



Drive Bay (Node A-D)	Description
0 – 1	2 Hot-swap 2.5" PCIe 5.0 NVMe/SAS/SATA Drive Bays (from CPU1)
2 – 5	4 Hot-swap 2.5" PCIe 4.0 NVMe/SAS/SATA Drive Bays (from CPU2)

(Rear View – System)



Per Node (Node A-D)	Slot Description
1	PCIe 5.0 x16 LP
2	PCIe 5.0 x16 LP
AI	PCIe 5.0 x16 AIOM

CPU1 CPU2

System Cooling	Fans: 4x 16K RPM Counter Rotating 80x80x56mm Fan(s) Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies
System BIOS	BIOS Type: AMI 32MB Flash ROM
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8+4 Phase-switching voltage regulator
Dimensions and Weight	Weight: Gross Weight: 96.6 lbs (43.8 kg) Net Weight: 66.1 lbs (30 kg) Available Color: Black front & silver body
Operating Environment	RoHS Compliant Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)
Motherboard	**Super X14DBT-B**
Chassis	**CSE-217BQ2-R3K60P**

©2024 Copyright Super Micro Computer, Inc. All rights reserved. *Product specifications may change without notice